

ASMT-Mx00

Moonstone™ 1 W Power LED Light Source



Data Sheet



Description

1W Power LED Light Source is a high performance energy efficient device which can handle high thermal and high driving current. The exposed pad design has excellent heat transfer from the package to the motherboard.

The Warm White Power LED is available in various color temperature ranging from 2600K to 4000K. The product has high Color Rendering Index (CRI) which provides excellent color perception and visual clarity.

The low profile package design is suitable for a wide variety of applications especially where height is a constraint.

The package is compatible with reflow soldering process. This will give more freedom and flexibility to the light source designer.

Applications

- Portable (flash light, bicycle head light)
- Reading light
- Architectural lighting
- Garden lighting
- Decorative lighting

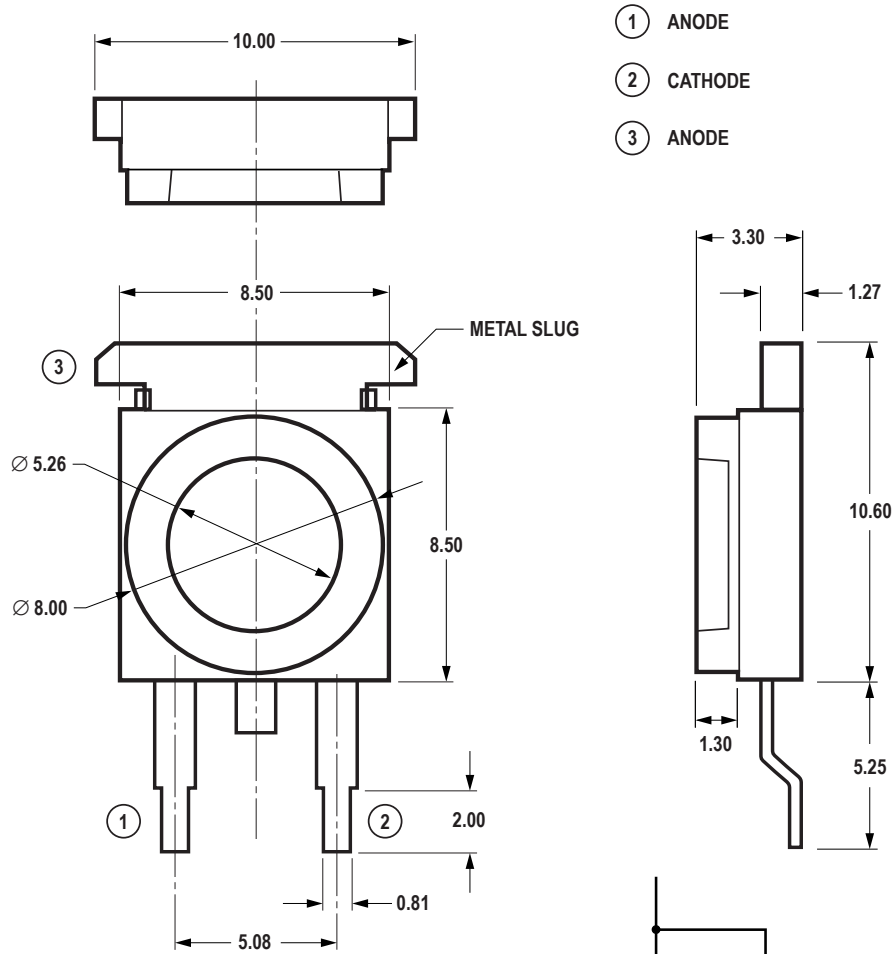
Features

- Available in Red, Amber, Green, Blue, Cool White and Warm White color
- Energy efficient
- Exposed pad for excellent heat transfer
- Suitable for reflow soldering process
- High current operation
- Long operation life
- Wide viewing angle
- Silicone encapsulation
- ESD Class HBM Class 3B, > 8000
- MSL 2A for InGaN products
- MSL 4 for AllInGaP products

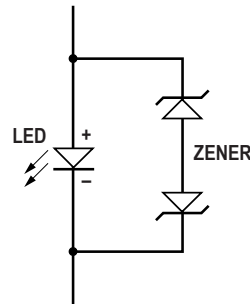
Specifications

- AllInGaP Technology for Red and Amber
- 2.4V, 350mA (typical) for AllInGaP Technology
- InGaN technology
- 3.6 V, 350 mA (typical)
- 120 viewing angle

Package Dimensions



- NOTES:
1. ALL DIMENSIONS IN MILLIMETERS.
2. TOLERANCE IS ± 0.1 mm UNLESS OTHERWISE SPECIFIED.



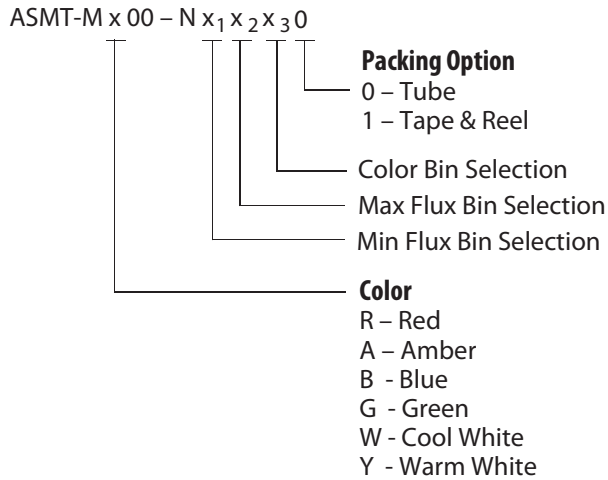
Device Selection Guide at Junction Temperature $T_j = 25^\circ\text{C}$

Color	Part Number	Luminous Flux, $\phi_v^{[1,2]}$ (lm)			Test Current (mA)	Dice Technology
		Min.	Typ.	Max.		
Red	ASMT-MR00-AGH00	25.5	35.0	43.0	350	AllInGaP
Red	ASMT-MR00-AHJ00	33.0	40.0	56.0	350	AllInGaP
Amber	ASMT-MA00-AGH00	25.5	35.0	43.0	350	AllInGaP
Green	ASMT-MG00	25.5	40.0	73.0	350	InGaN
Blue	ASMT-MB00	5.5	10.0	19.5	350	InGaN
Cool White	ASMT-MW00	43.0	60.0	73.0	350	InGaN
Warm White	ASMT-MY00	43.0	50.0	73.0	350	InGaN

Notes

1. ϕ_v is the total luminous flux output as measured with an integrating sphere at 25 ms mono pulse condition.
2. Flux tolerance is $\pm 10\%$.

Part Numbering System



Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$)

Parameter	ASMT-Mx00	Units
DC Forward Current ^[1]	350	mA
Peak Pulsing Current ^[2]	500	mA
Power Dissipation for AlInGaP	1050	mW
Power Dissipation for InGaN	1400	mW
LED Junction Temperature for AlInGaP	125	°C
LED Junction Temperature for InGaN	110	°C
Operating Ambient Temperature Range	-40 to +100	°C
Storage Temperature Range	-40 to +120	°C

Notes:

- DC forward current – derate linearly based on Figure 5 for AlInGaP & Figure 11 for InGaN.
- Pulse condition duty factor = 10%, Frequency = 1kHz.

Optical Characteristics ($T_A = 25^\circ\text{C}$)

Part Number	Color	Peak Wavelength	Dominant Wavelength	Viewing Angle	Luminous Efficiency
		λ_{PEAK} (nm) Typ.	λ_D ^[1] (nm) Typ.	$2\theta_{1/2}$ ^[2] (Degrees) Typ.	(lm/W) Typ.
ASMT-MR00-AGH00	Red	635	625	120	42
ASMT-MR00-AHJ00	Red	635	625	120	48
ASMT-MA00-AGH00	Amber	598	590	120	42
ASMT-MG00	Green	519	525	120	32
ASMT-MB00	Blue	460	467	120	8

Part Number	Color	Correlated Color Temperature, CCT (Kelvin)		Viewing Angle	Luminous Efficiency
		Min.	Max.	$2\theta_{1/2}$ ^[2] (Degrees) Typ.	(lm/W) Typ.
ASMT-MW00	Cool White	4000	10000	110	48
ASMT-MY00	Warm White	2600	4000	110	40

Notes:

- The dominant wavelength, λ_D , is derived from the CIE Chromaticity Diagram and represents the color of the device.
- $\theta_{1/2}$ is the off-axis angle where the luminous intensity is 1/2 the peak intensity.

Electrical Characteristic ($T_A = 25^\circ\text{C}$)

Dice Type	Forward Voltage V_F (Volts) @ $I_F = 350\text{mA}$		Reverse Voltage V_R (Volts)	Thermal Resistance $R_{\theta_{j-ms}}$ ($^\circ\text{C/W}$) ^[1]
	Typ.	Max.	Max.	Typ.
AllnGaP	2.4	3.0	5	12
InGaN	3.6	4.0	5	10

Notes:

- $R_{\theta_{j-ms}}$ is Thermal Resistance from LED junction to metal slug.

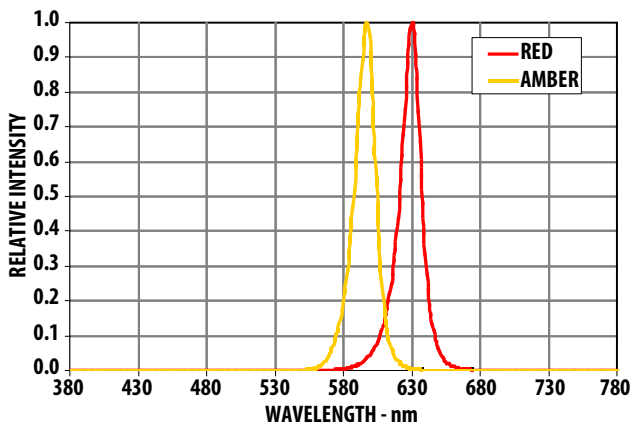


Figure 1. Relative Intensity vs. Wavelength for AllnGaP

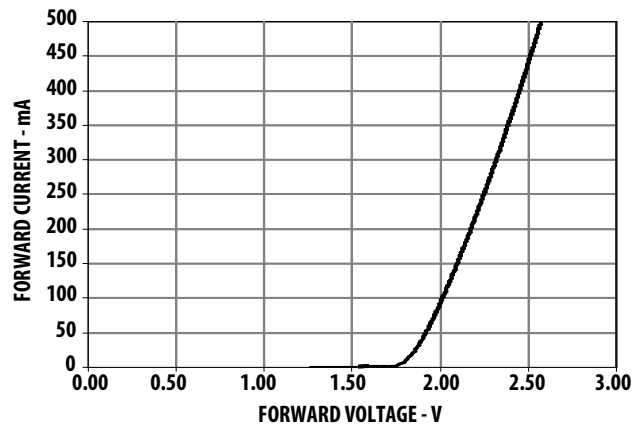


Figure 2. Forward Current vs Forward Voltage for AllnGaP

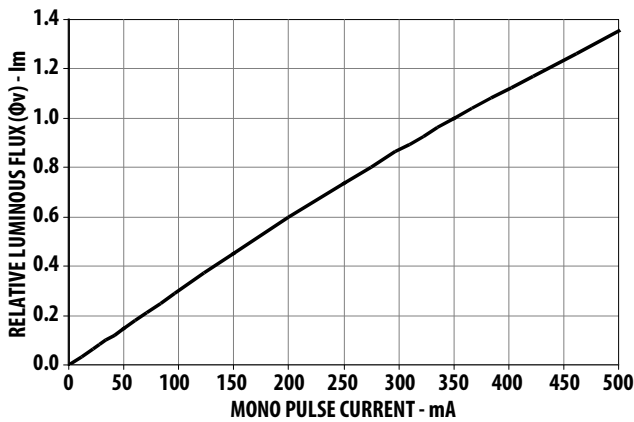


Figure 3. Relative Luminous Flux vs. Mono Pulse Current for AllnGaP

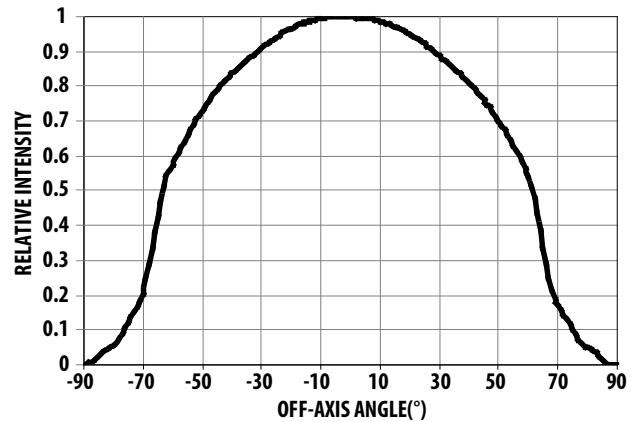


Figure 4. Radiation Pattern for AllnGaP

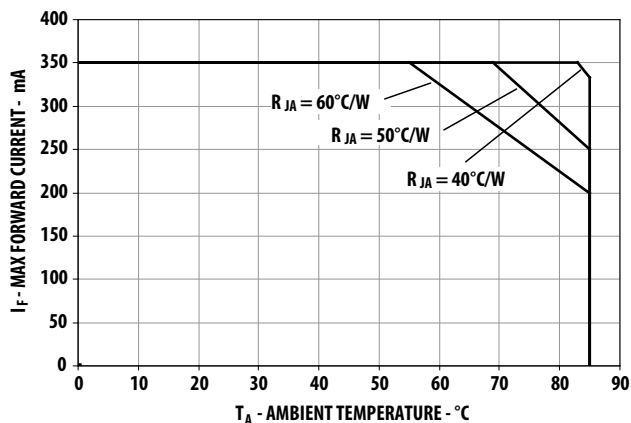


Figure 5. Maximum forward current vs. ambient temperature for AllnGaP
Derated based on $T_{j,MAX} = 125^\circ\text{C}$, $R_{\theta_{jA}} = 40^\circ\text{C/W} / 50^\circ\text{C/W}$ and 60°C/W

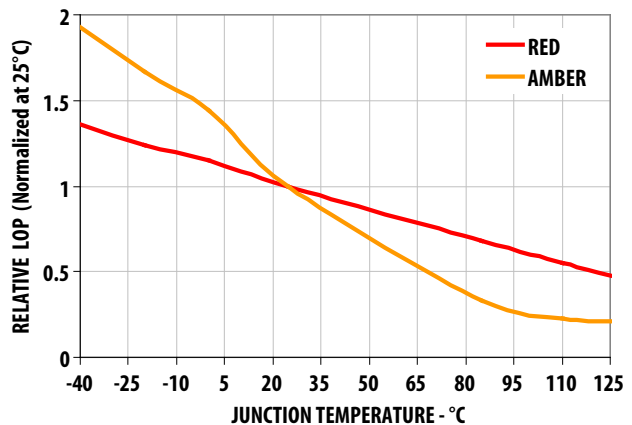


Figure 6. Relative LOP (Normalized at 25°C) vs. junction temperature for AllnGaP

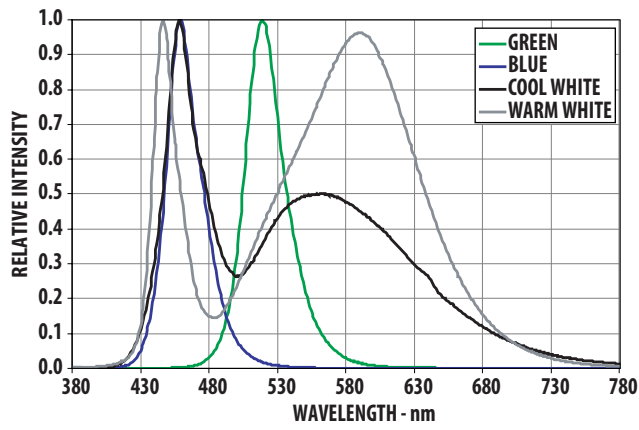


Figure 7. Relative Intensity vs. Wavelength for InGaN

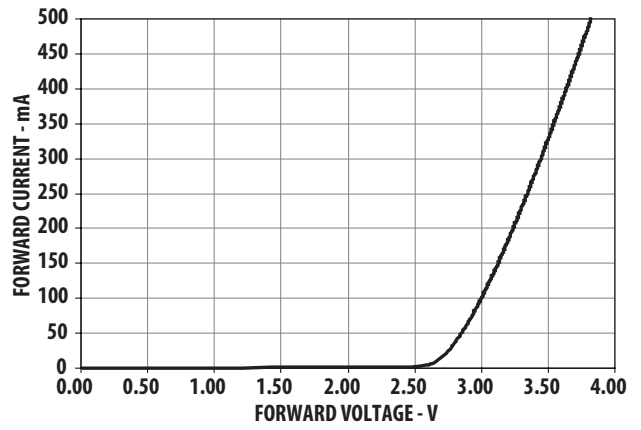


Figure 8. Forward Current vs. Forward Voltage for InGaN

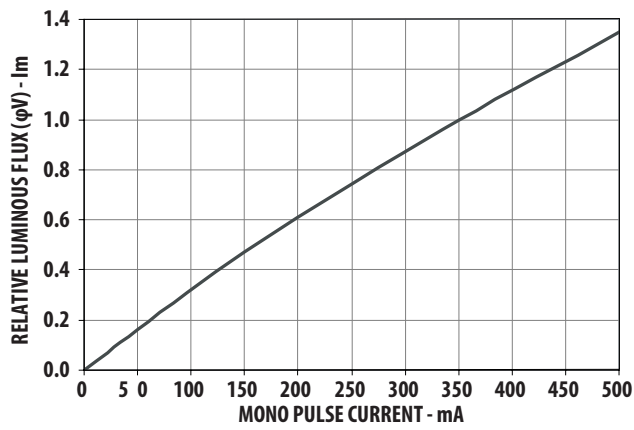


Figure 9. Relative Luminous Flux vs. Mono Pulse Current for InGaN

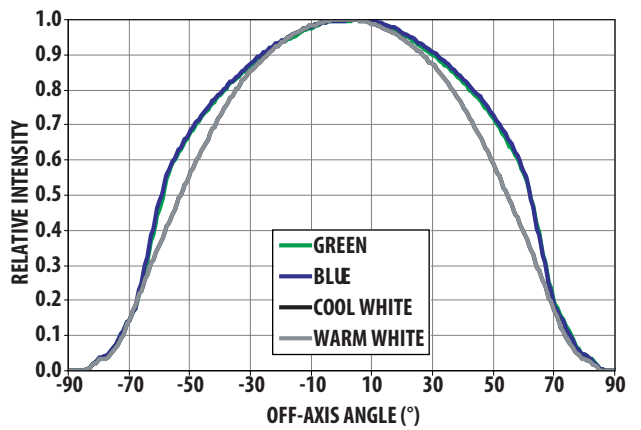


Figure 10. Radiation Pattern for InGaN

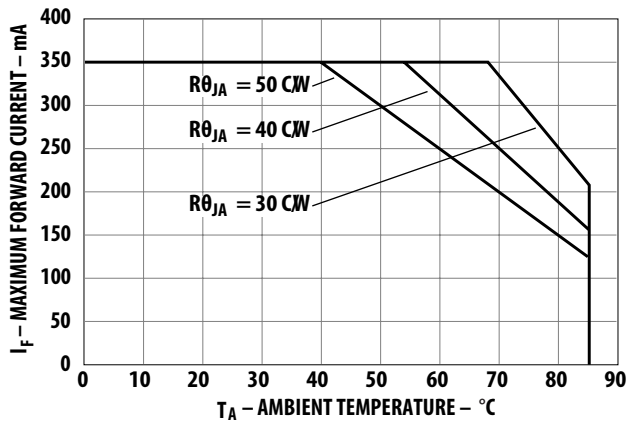


Figure 11. Maximum Forward Current vs. Ambient Temperature for InGaN
Derated based on $T_{j,MAX} = 110^{\circ}C$, $R_{\theta_{JA}} = 30^{\circ}C/W$, $40^{\circ}C/W$ and $50^{\circ}C/W$

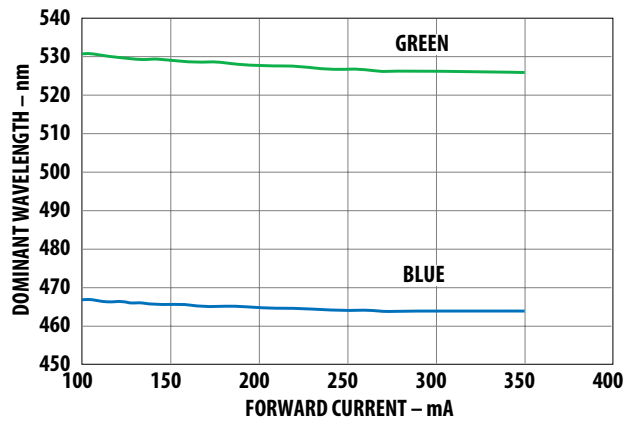


Figure 12. Dominant wavelength vs. forward current - InGaN devices

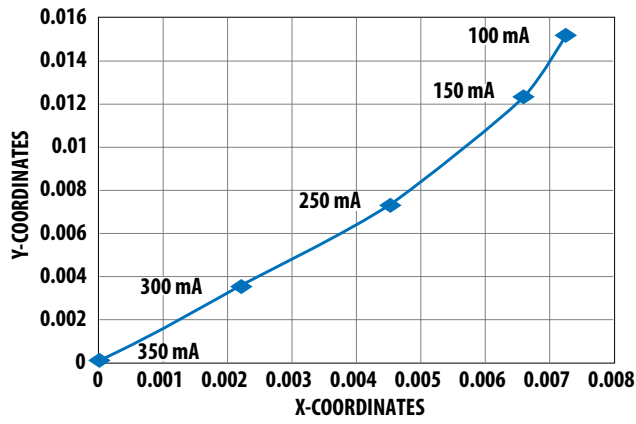


Figure 13. Chromaticity shift vs. current
 *Note: (x,y) values @ 350 mA reference to (0,0)

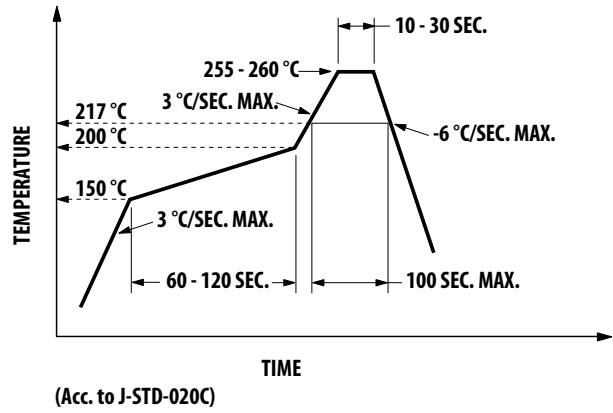


Figure 14. Recommended reflow soldering profile
 (Acc. to J-STD-020C)

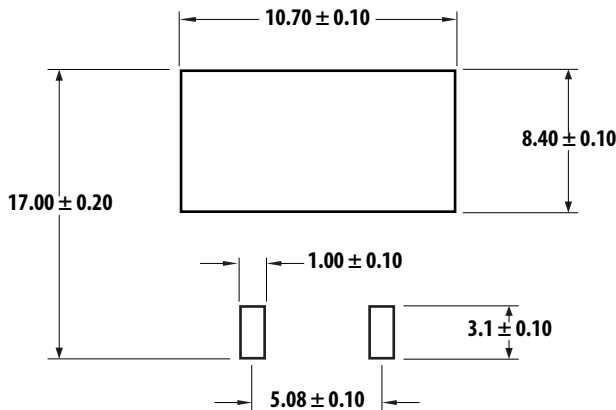


Figure 15. Recommended soldering land pattern

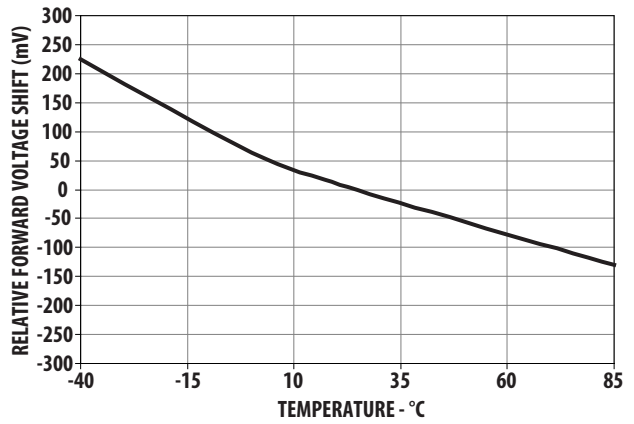


Figure 16. Temperature vs. relative forward voltage shift

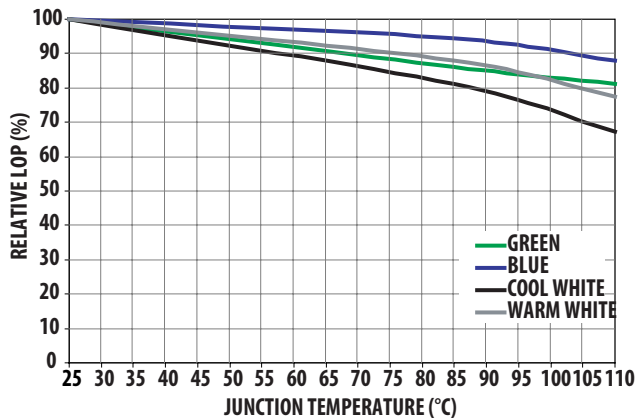


Figure 17. Relative LOP vs Junction Temperature for InGaN Devices

Flux Bin Limit (for reference only) [x_1, x_2]

Bin	Flux (lm) at 350mA	
	Min	Max
A	5.5	7.0
B	7.0	9.0
C	9.0	11.5
D	11.5	15.0
E	15.0	19.5
F	19.5	25.5
G	25.5	33.0
H	33.0	43.0
J	43.0	56.0
K	56.0	73.0

Tolerance for each bin limits is $\pm 10\%$

Color Bin Selections [X_3]

Individual reel will contain parts from one full bin only

Cool White

O	Full Distribution
A	A only
B	B only
C	C only
D	D only
E	E only
F	F only
G	G only
H	H only
Z	A and B only
Y	B and C only
W	C and D only
V	D and E only
U	E and F only
T	F and G only
S	G and H only
Q	A, B and C only
P	B, C and D only
N	C, D and E only
M	D, E and F only
L	E, F and G only
K	F, G and H only
J	Special Color Bin
1	A, B, C and D only
2	E, F, G and H only
3	B, C, D and E only
4	C, D, E and F only
5	A, B, C, D and E only
6	B, C, D, E, and F only

Color Bin Limits

Amber	Min. (nm)	Max. (nm)
A	582.0	584.5
B	584.5	587.0
C	587.0	589.5
D	589.5	592.0
E	592.0	594.5

Blue	Min. (nm)	Max. (nm)
A	460.0	465.0
B	465.0	470.0
C	470.0	475.0
D	475.0	480.0

Green	Min. (nm)	Max. (nm)
A	515.0	520.0
B	520.0	525.0
C	525.0	530.0
D	530.0	535.0

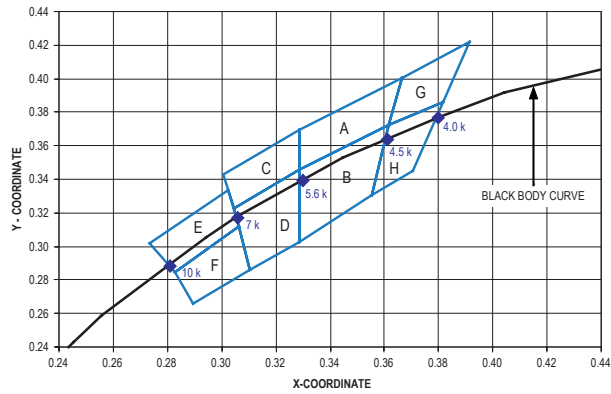
Warm White

O	Full Distribution
A	A only
B	B only
C	C only
D	D only
E	E only
F	F only
Z	A and B only
Y	B and C only
W	C and D only
V	D and E only
U	E and F only
Q	A, B and C only
P	B, C and D only
N	C, D and E only
M	D, E and F only
J	Special Color Bin
1	A, B, C and D only
2	E, F, G and H only
3	B, C, D and E only
4	C, D, E and F only
5	A, B, C, D and E only
6	B, C, D, E, and F only

Primary Color Binning

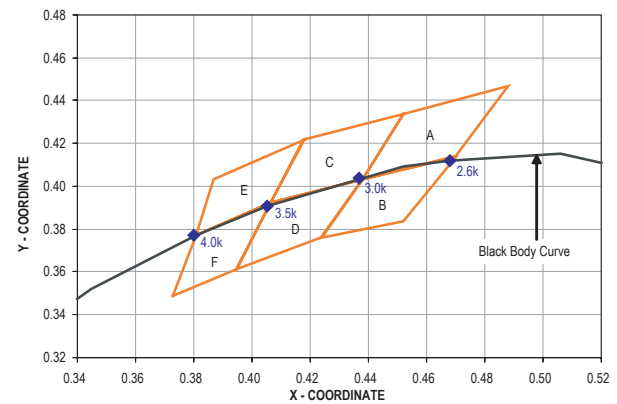
Cool White	Color Limits (Chromaticity Coordinates)				
Bin A	X	0.367	0.362	0.329	0.329
	Y	0.400	0.372	0.345	0.369
Bin B	X	0.362	0.356	0.329	0.329
	Y	0.372	0.330	0.302	0.345
Bin C	X	0.329	0.329	0.305	0.301
	Y	0.369	0.345	0.322	0.342
Bin D	X	0.329	0.329	0.311	0.305
	Y	0.345	0.302	0.285	0.322
Bin E	X	0.303	0.307	0.283	0.274
	Y	0.333	0.311	0.284	0.301
Bin F	X	0.307	0.311	0.290	0.283
	Y	0.311	0.285	0.265	0.284
Bin G	X	0.388	0.379	0.362	0.367
	Y	0.417	0.383	0.372	0.400
Bin H	X	0.379	0.369	0.356	0.362
	Y	0.383	0.343	0.330	0.372

Tolerances ± 0.01



Warm White	Color Limits (Chromaticity Coordinates)				
Bin A	X	0.452	0.488	0.470	0.438
	Y	0.434	0.447	0.414	0.403
Bin B	X	0.438	0.470	0.452	0.424
	Y	0.403	0.414	0.384	0.376
Bin C	X	0.407	0.418	0.452	0.438
	Y	0.393	0.422	0.434	0.403
Bin D	X	0.395	0.407	0.438	0.424
	Y	0.362	0.393	0.403	0.376
Bin E	X	0.381	0.387	0.418	0.407
	Y	0.377	0.404	0.422	0.393
Bin F	X	0.373	0.381	0.407	0.395
	Y	0.349	0.377	0.393	0.362

Tolerances ± 0.01



Sub-Color Binning

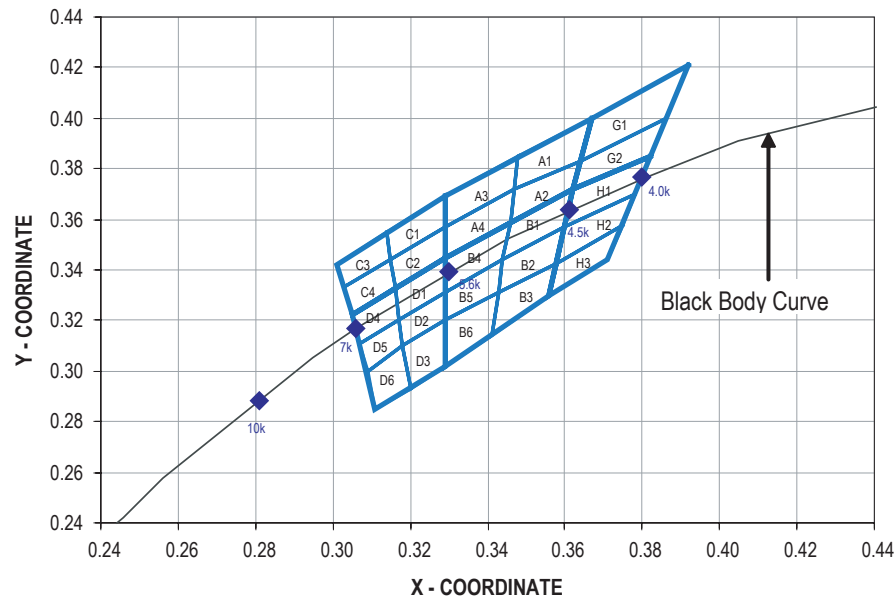
(Only Applicable for Color Bin A to Bin D and Bin G to Bin H)

Color Limits

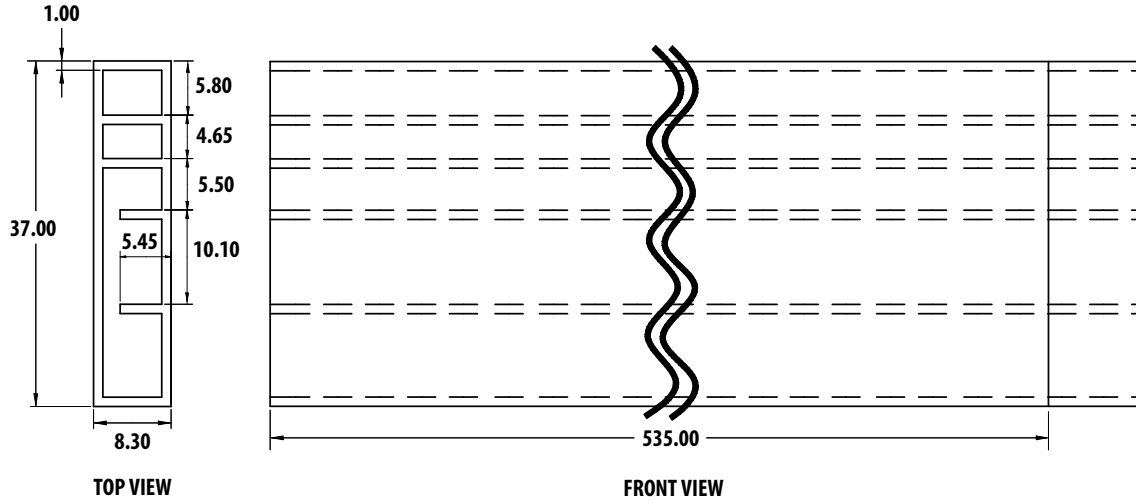
Cool White	(Chromaticity Coordinates)				
Bin A1	X	0.364	0.367	0.348	0.347
	Y	0.383	0.400	0.385	0.372
Bin A2	X	0.364	0.362	0.346	0.347
	Y	0.383	0.372	0.359	0.372
Bin A3	X	0.329	0.329	0.348	0.347
	Y	0.357	0.369	0.385	0.372
Bin A4	X	0.329	0.329	0.347	0.346
	Y	0.345	0.357	0.372	0.359
Bin B1	X	0.362	0.360	0.344	0.346
	Y	0.372	0.357	0.344	0.359
Bin B2	X	0.360	0.358	0.343	0.344
	Y	0.357	0.343	0.331	0.344
Bin B3	X	0.358	0.356	0.341	0.343
	Y	0.343	0.330	0.314	0.331
Bin B4	X	0.329	0.329	0.346	0.344
	Y	0.331	0.345	0.359	0.344
Bin B5	X	0.329	0.344	0.343	0.329
	Y	0.331	0.344	0.331	0.320
Bin B6	X	0.343	0.341	0.329	0.329
	Y	0.331	0.314	0.302	0.320
Bin C1	X	0.329	0.329	0.315	0.314
	Y	0.369	0.357	0.344	0.355
Bin C2	X	0.329	0.329	0.316	0.315
	Y	0.357	0.345	0.333	0.344
Bin C3	X	0.314	0.315	0.303	0.301
	Y	0.355	0.344	0.333	0.342
Bin C4	X	0.315	0.316	0.305	0.303
	Y	0.344	0.333	0.322	0.333

Cool White	(Chromaticity Coordinates)				
Bin D1	X	0.329	0.329	0.317	0.316
	Y	0.345	0.331	0.320	0.333
Bin D2	X	0.329	0.329	0.318	0.317
	Y	0.331	0.320	0.310	0.320
Bin D3	X	0.329	0.329	0.320	0.318
	Y	0.320	0.302	0.293	0.310
Bin D4	X	0.316	0.317	0.307	0.305
	Y	0.333	0.320	0.311	0.322
Bin D5	X	0.317	0.318	0.309	0.307
	Y	0.320	0.310	0.300	0.311
Bin D6	X	0.318	0.320	0.311	0.309
	Y	0.310	0.293	0.285	0.300
Bin G1	X	0.392	0.386	0.364	0.367
	Y	0.421	0.400	0.383	0.400
Bin G2	X	0.386	0.382	0.362	0.364
	Y	0.400	0.385	0.372	0.383
Bin H1	X	0.382	0.378	0.360	0.362
	Y	0.385	0.370	0.357	0.372
Bin H2	X	0.378	0.375	0.358	0.360
	Y	0.370	0.358	0.343	0.357
Bin H3	X	0.375	0.371	0.356	0.358
	Y	0.358	0.344	0.330	0.343

Tolerances ± 0.01

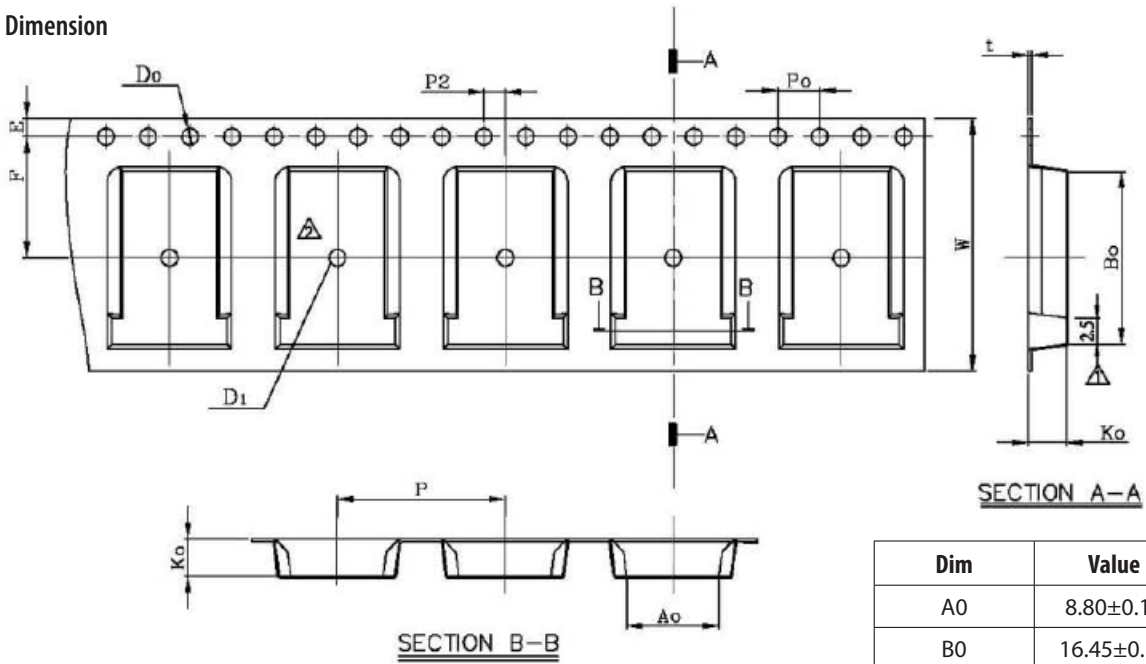


Packing Tube - Option 0



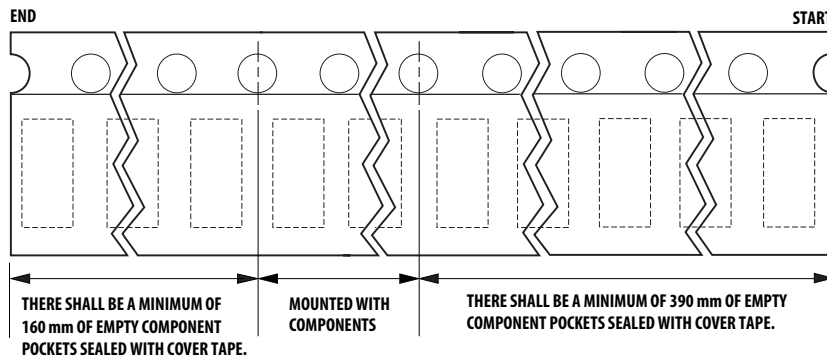
Tape & Reel - Option 1

Tape Dimension

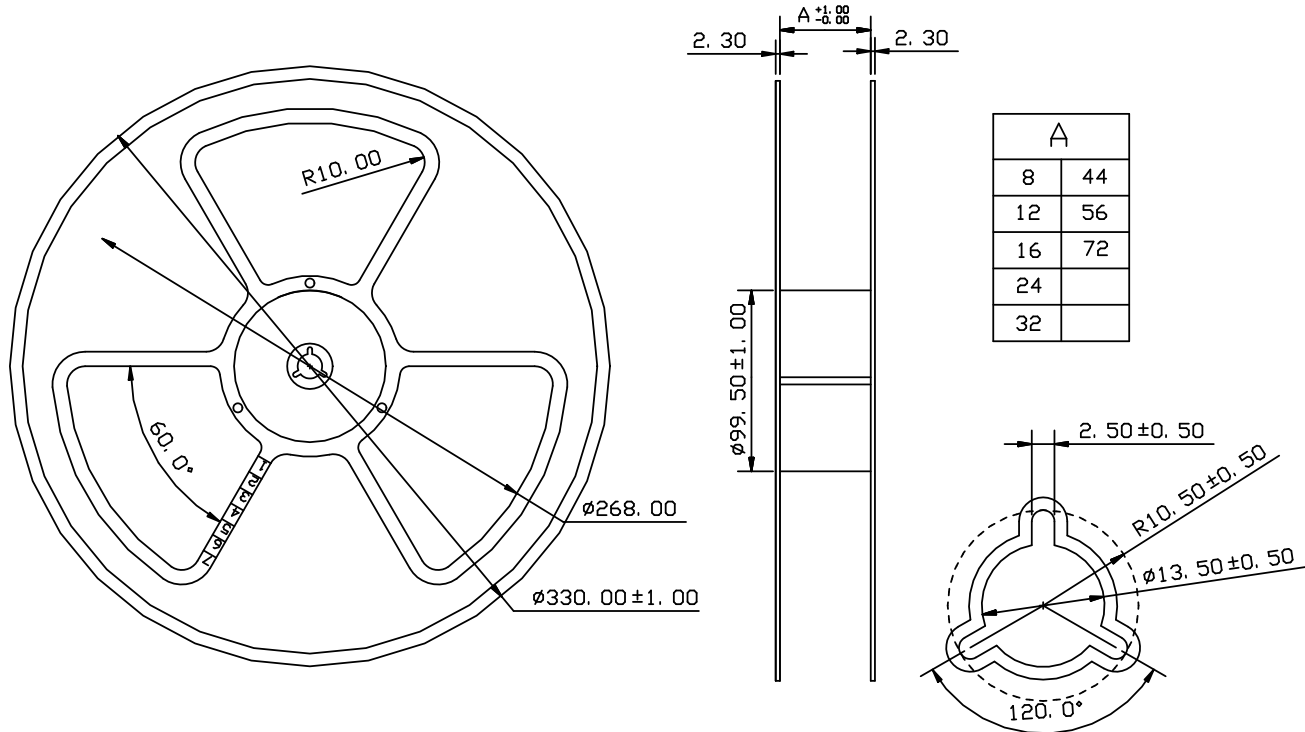


Dim	Value
A0	8.80±0.10
B0	16.45±0.10
K0	3.60±0.10
W	24.0±0.10
P	16.0±0.10
Qty/Reel	250EA

Unit: mm



Reel Dimensions



Handling Precaution

The encapsulation material of the product is made of silicone for better reliability of the product. As silicone is a soft material, please do not press on the silicone or poke a sharp object onto the silicone. These might damage the product and cause premature failure. During assembly or handling, the unit should be held on the body (white epoxy).

This product is classified as moisture sensitive level 2A for InGaN devices and MSL 4 for AllnGaP devices

When the bag is opened, parts required to mount within the period shown below:

MSL 2A – 672 hours of factory conditions $\leq 30^{\circ}\text{C}/60\%\text{RH}$, and stored at $<10\%\text{RH}$.

MSL 4 – 72 hours of factory conditions $\leq 30^{\circ}\text{C}/60\%\text{RH}$, and stored at $<10\%\text{RH}$.

Devices required bake, before mounting if:

- The humidity indicator card is $>10\%$ when read at $23 \pm 5^{\circ}\text{C}$
- The pack has been opened for more than 672 hours for MSL 2a product (InGaN) and 72 hours for MSL 4 products (AllnGaP)

Baking recommended condition: $60 \pm 5^{\circ}\text{C}$ for 20 hours

DISCLAIMER

AVAGO'S PRODUCTS AND SOFTWARE ARE NOT SPECIFICALLY DESIGNED, MANUFACTURED OR AUTHORIZED FOR SALE AS PARTS, COMPONENTS OR ASSEMBLIES FOR THE PLANNING, CONSTRUCTION, MAINTENANCE OR DIRECT OPERATION OF A NUCLEAR FACILITY OR FOR USE IN MEDICAL DEVICES OR APPLICATIONS. CUSTOMER IS SOLELY RESPONSIBLE, AND WAIVES ALL RIGHTS TO MAKE CLAIMS AGAINST AVAGO OR ITS SUPPLIERS, FOR ALL LOSS, DAMAGE, EXPENSE OR LIABILITY IN CONNECTION WITH SUCH USE.

For product information and a complete list of distributors, please go to our web site: www.avagotech.com

Avago, Avago Technologies, and the A logo are trademarks of Avago Technologies in the United States and other countries. Data subject to change. Copyright © 2005-2008 Avago Technologies. All rights reserved. Obsoletes AV01-0668EN AV02-0129EN - July 2, 2008

AVAGO
TECHNOLOGIES